CBC3 specifications

now in middle of CBC3 design phase

specifications agreed and document available here:

http://www.hep.ph.ic.ac.uk/~dmray/CBC documentation/CBC3 Technical Spec V1p03.doc

will summarise today

(some repetition of previous presentations, but worth it now specs finalised)

Mark Raymond, CMS Tracker Week, Tracker Phase 2 Electronics, May 2015

CBC3 block diagram



will go through each block in turn, explaining functionality and quoting specs.

CBC3 front end amplifier

front end will be optimised **specifically** for n-on-p sensor polarity AC coupled no DC current tolerance required strip length 5 cm (~8 pF)

pulse shaping peaking time <20 nsec return to baseline within 50 nsec

overload recovery (hips response)

an individual channel should respond to a normal size signal

< 2.5 usec following hip signal up to 4 pC

(spec. based on what is achievable)



target ENC < 1000e

front end optimisation progressing

simulation shows signals in comparator 2.5 fC -> 12.5 fC, 2.5 fC steps comparator threshold at 1 fC overall pulse length < 50 nsec





3

comparators and channel mask

comparator

individually tunable offset

improved (10-bit) resolution for global threshold

=> 1 mV LSB (~125e)

channel mask

important to suppress fake triggers and also to limit occupancy after sparsification



hit detect

samples output from comparator using programmable phase 40 MHz clock from DLL (1 nsec resolution)

needs to be sensitive to variety of input conditions



single pulse at amp. O/P. Comparator O/P fires. Hit detect produces output at next 40 MHz clock edge



for two clock cycles

top & bottom channel swap

modules mounted above and below support structure will be flipped (probably)

=> seed and window layers will also be flipped unless do something about it

(expect lower efficiency when seeding from outer layer because of scattering and conversions -> more hits in outer layer which don't correspond to valid stub)

simplest thing is to swap channels on chip

module flipped

14

13

11

13

1<->2, 3<->4, 5<->6.....

9

11



seed laver

14

12

10

8

back to seed layer nearer

interaction point

6

4

2

6

seed laver 10 12 14 2 4 6 8

r∧

window layer

3

5

seed layer nearer interaction point

now window layer nearer interaction point

7

9

window laver

3

5

cluster width discrimination

CBC2: clusters ≤ **3** strips accepted

2 strip cluster assigned to one of the strips involved

CBC3: clusters ≤ **4** strips accepted

2 & 4 strip clusters assigned to midposition

=> 1/2 strip cluster position resolution

=> 8-bit cluster address





CBC3 stub generated if cluster in seed layer corresponds to cluster found within window in other layer

window width programmable up to ± 7 strips (± 14 half strips)

window can be offset, 4 domains / chip (=> 32 across module)

offset programmable up to ± 3 strips (± 6 half strips)

position of cluster in window indicates direction of stub -> this is the **bend** information

5 bits bend info locates cluster to individual 1/2 strip position if widest window selected

stub gathering logic + bend lookup formatting

up to 3 stub addresses + associated bend info can be passed to **bend lookup formatting** block every BX

no priority logic - 1st 3 stubs only

more than 3 -> stubs overflow bit set in O/P data packet

13 bits / stub => 39 bits total

5 bits bend info reduced to 4 bits using programmable lookup table (mapping depends on location in tracker)

stubs gathering logic and bend lookup formatting logic described in more detail last time:

https://indico.cern.ch/event/360684/session/0/contribution/1/material/slides/1.pdf





< 0.001% triggers rejected @ 1 MHz for buffer depth 32



pipeline & PISO shift register

32 deep buffer for triggered events awaiting readout

=> very low inefficiency for trigger rate up to 1MHz

512 deep pipeline => up to 12.8 usec latency

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data packet assembly & transmission

6 differential outputs running at 320 Mbps

25 ns	S1	S2	S 3	B1	B3	R
	S1	S2	S 3	B1	B3	R
	S1	S2	S3	B1	B3	R
	S1	S2	S 3	B1	B3	R
	S1	S2	S 3	B2	SoF	R
	S1	S2	S 3	B2	OR254	R
	S1	S2	S 3	B2	Error	R
\downarrow	S1	S2	S3	B2	Sync	R

S = Cluster address, B = Bend data SoF = Stub Overflow (>3 Stubs) OR254 = any unmasked channel over threshold Error = latency OR FIFO overflow error Sync = For synchronisation with CICR = Triggered readout data (remains unsparsified)



data packet assembly & transmission

trigger rate capability to 1 MHz

9 bits pipe

address

2 start bits

2 error bits

data frame comprises

2 start bits 2 error bits (latency & FIFO overflow) 9 bits pipe address (triggered pipeline location) 9 bits L1 counter reset by fast reset OR dedicated reset e.g. every orbit 254 bits strip readout data





slow control

I2C @ 1 MHz

test pulse trigger L1 counter reset

CBC3 miscellaneous

clocks 40 MHz and 320 MHz differential

test pulse feature same as CBC2

SEU immunity

I2C register immunity to be improved by using Whitaker cells for results see <u>http://www.hep.ph.ic.ac.uk/~dmray/CBC documentation/Phase 2 SEU Kirika Nov 14.pdf</u>

ionizing radiation tolerance

pipeline cell design to be modified to eliminate leakage effect at low doses for results see <u>http://www.hep.ph.ic.ac.uk/~dmray/CBC_documentation/Phase_2_TID_Davide_Nov_14.pdf</u>

power

1.2 V \pm 10% on-chip LDO to generate analogue power rail target power consumption for 5 cm strips 450 uW/channel

pads

250 um pitch, same as CBC2 wire-bondable column for probing and other tests

summary

CBC3 design underway specs are defined and a document is available have summarised most of contents here MOSIS submission planned for February 2016 => chips in hand ~ May MDSIS Submission planned for February 2016 => chips in hand ~ May

EXTRA

CBC3 status

Complete

Preliminary Layout

M.Prydderch

To do

In progress



- Analogue front end re-designed. Needs layout & further simulation.
- Hit Detect Schematic & simulations complete. Needs layout.
- Channel Mask incorporated in Hit Detect. I2C registers need to be added.
- Stub finding logic blocks complete.
- Bend look-up table completed to preliminary layout. I2C registers need to be added.
- Data assembly blocks are completed to preliminary layout.
- Serial Fast Control designed and simulated. Needs layout.
- Pipeline SRAM cell modified. Pipeline needs extending & drivers checked.
- I2C register cell redesigned. Layout in progress. Needs further simulation.
- Ibias current reference redesigned. Layout in progress. Needs further simulation.
- New 10 bit DAC for VCTH not started.
- Nearest Neighbour pads not started (Top level layout exercise)
- 2nd DLL not yet investigated.
- Top level layout assembly &7 verification not yet started.

hit detect logic



flexibility included to allow choice of output to following logic mainly for diagnostic purposes

also includes HIP suppression circuit to block output if comparator high for longer than N clock cycles N programmable up to 7

CBC2 issues to address (in CBC3)

- leakage current in pipeline at low ionizing doses
 <u>http://www.hep.ph.ic.ac.uk/~dmray/CBC_documentation/Phase_2_TID_Davide_Nov_14.pdf</u>
 enclosed NMOS devices now implemented
- I2C register SEU immunity could be better http://www.hep.ph.ic.ac.uk/~dmray/CBC_documentation/Phase_2_SEU_Kirika_Nov_14.pdf now plan to use Whitaker cells for registers
- CM effect in electrons polarity mode shows up when threshold low and many channels firing traced to postamp feedback FET biasing <u>http://www.hep.ph.ic.ac.uk/~dmray/systems_talks/2015/CBC2_CM_systems_Jan2015.pdf</u> a new method for biasing the feedback FET has been found
- so-called "shadow effect"

when signal injected into many channels, other channels fire, but ~50ns later traced to coupling through preamp cascode bias

http://www.hep.ph.ic.ac.uk/~dmray/systems_talks/2015/CBC2_shadow_effect_Apr_2015.pdf preamp cascode now individually biased using regulated cascode circuit